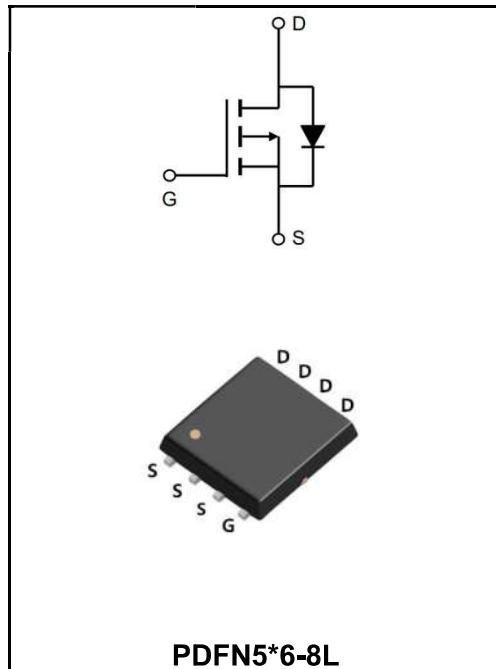


**-60V P-CHANNEL ENHANCEMENT MODE MOSFET**
**MAIN CHARACTERISTICS**

$I_D$	-45A
$V_{DSS}$	-60V
$R_{DS(on)-typ}(@V_{GS}=-10V)$	< 25mΩ (Type: 19 mΩ)


**Application**

- ◆ Lithium battery protection
- ◆ Wireless impact
- ◆ Mobile phone fast charging

**Product Specification Classification**

Part Number	Package	Marking	Pack
YFW45P06NF	PDFN5*6-8L	YFW 45P06NF XXXXX	5000PCS/Tape

**Maximum Ratings at  $T_c=25^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbols	Value	Units
Drain-Source Voltage	$V_{DS}$	-60	V
Gate - Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current, $V_{GS} @ -10V^1$ @ $T_c=25^\circ\text{C}$	$I_D$	-45	A
Continuous Drain Current, $V_{GS} @ -10V^1$ @ $T_c=100^\circ\text{C}$	$I_D$	-28	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	-85	A
Single Pulse Avalanche Energy <sup>3</sup>	$E_{AS}$	113	mJ
Avalanche Current	$I_{AS}$	47.6	A
Total Power Dissipation <sup>4</sup> @ $T_c=25^\circ\text{C}$	$P_D$	52.1	W
Storage Temperature Range	$T_{STG}$	-55 to +150	°C
Operating Junction Temperature Range	$T_J$	-55 to +150	°C
Thermal Resistance Junction-Ambient <sup>1</sup>	$R_{\theta JA}$	25.5	°C/W
Thermal Resistance Junction-Case <sup>1</sup>	$R_{\theta JC}$	2.4	°C/W

**Maximum Ratings at Tc=25°C unless otherwise specified**

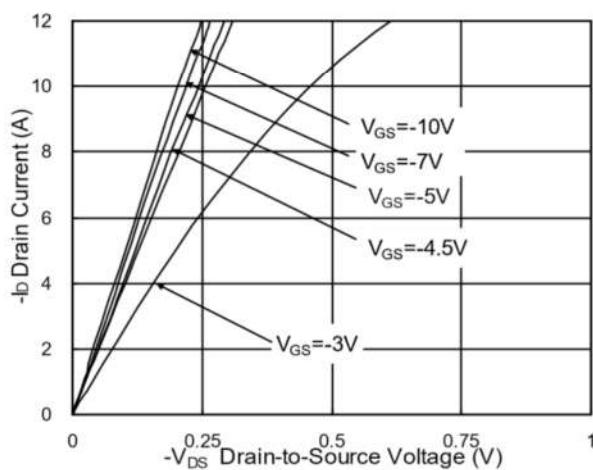
Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	BV <sub>DSS</sub>	-60	-68	-	V
BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =-1mA	ΔBV <sub>DSS/ΔTJ</sub>	-	-0.035	-	V/°C
Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-10A	R <sub>DS(ON)</sub>	-	19	25	mΩ
	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-8A		-	26	33	
Gate -Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250uA	V <sub>GS(th)</sub>	-1.0	-1.6	-2.5	V
V <sub>GS(th)</sub> Temperature Coefficient		ΔV <sub>GS(th)</sub>	-	4.28	-	mV/°C
Drain-Source Leakage Current	V <sub>DS</sub> =-48V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	I <sub>DSS</sub>	-	-	1	μA
	V <sub>DS</sub> =-48V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C		-	-	5	
Gate –Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	I <sub>GSS</sub>	-	-	±100	nA
Forward Transconductance	V <sub>DS</sub> =-10V , I <sub>D</sub> =-18A	g <sub>fs</sub>	-	23	-	S
Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz	R <sub>g</sub>	-	7	-	Ω
Total Gate Charge(-4.5V)	V <sub>DS</sub> =-20V V <sub>GS</sub> =-4.5V I <sub>D</sub> =-12A	Q <sub>g</sub>	-	25	-	nC
Gate-Source Charge		Q <sub>gs</sub>	-	6.7	-	
Gate-Drain Charge		Q <sub>gd</sub>	-	5.5	-	
Turn-on delay time	V <sub>DD</sub> =-15V V <sub>GS</sub> =-10V I <sub>D</sub> = -1A R <sub>G</sub> =3.3Ω	t <sub>d(on)</sub>	-	38	-	ns
Rise Time		T <sub>r</sub>	-	23.6	-	
Turn-Off Delay Time		t <sub>d(OFF)</sub>	-	100	-	
Fall Time		t <sub>f</sub>	-	6.8	-	
Input Capacitance	V <sub>DS</sub> =-15V V <sub>GS</sub> =0V f=1MHz	C <sub>iss</sub>	-	3536	-	pF
Output Capacitance		C <sub>oss</sub>	-	224	-	
Reverse Transfer Capacitance		C <sub>rss</sub>	-	141	-	
Continuous Source Current <sup>1.5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	I <sub>s</sub>	-	-	-35	A
Pulsed Source Current <sup>2.5</sup>		I <sub>SM</sub>	-	-	-70	A
Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25°C	V <sub>SD</sub>	-	-	-1	V

Note :

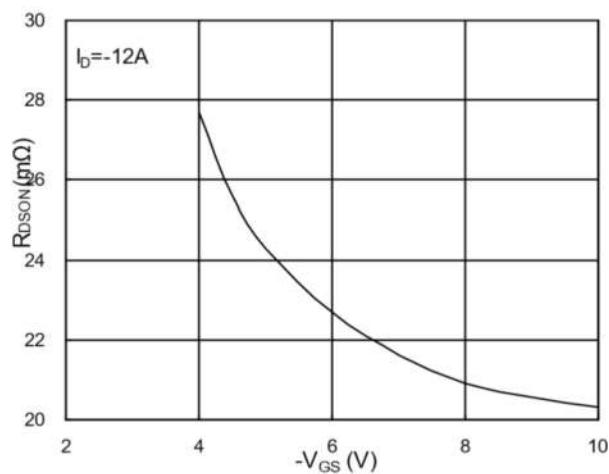
1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width ≈ 300us , duty cycle ≈ 2%
3. The EAS data shows Max. rating . The test condition is VDD=-48V,VGS =-10V,L=0.1mH,IAS =-47.6A
4. The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation.

**Ratings and Characteristic Curves**

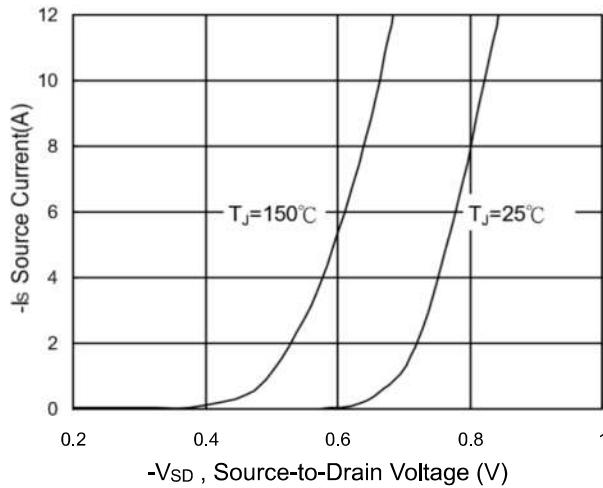
**Typical Characteristics**



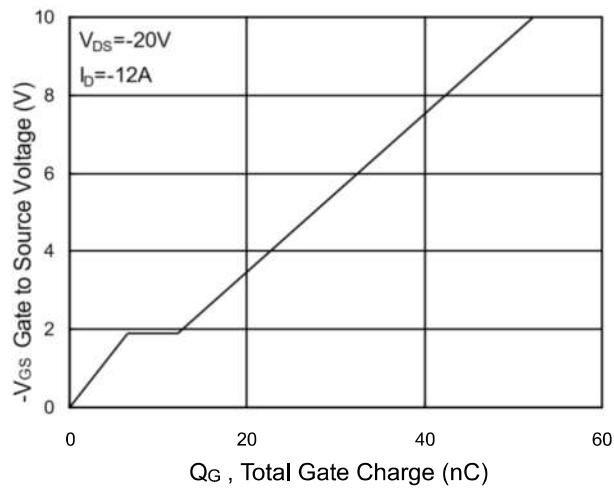
**Fig.1 Typical Output Characteristics**



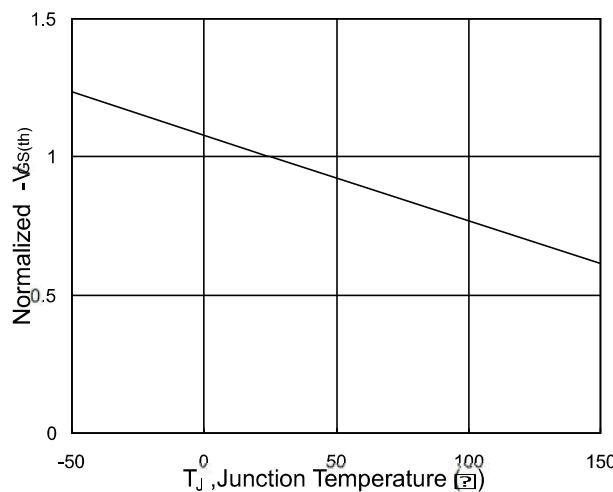
**Fig.2 On-Resistance v.s Gate-Source**



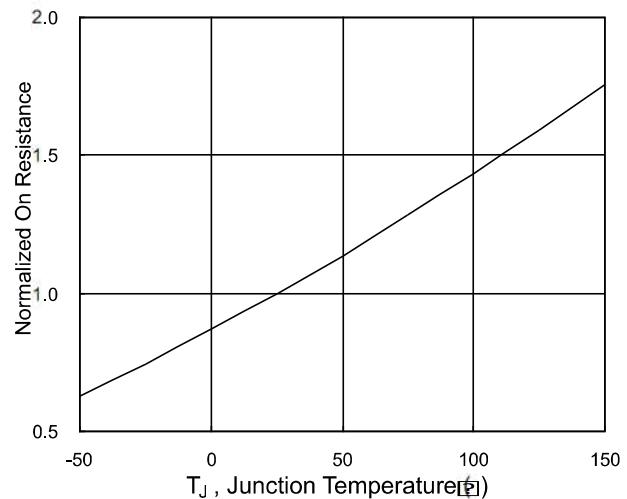
**Fig.3 Forward Characteristics Of Reverse**



**Fig.4 Gate-Charge Characteristics**

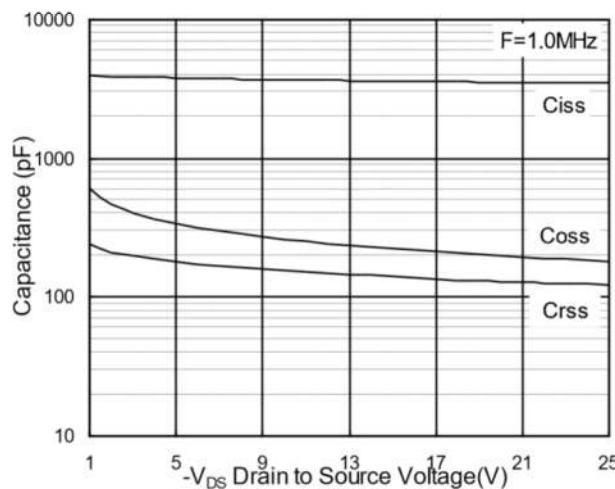


**Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$**

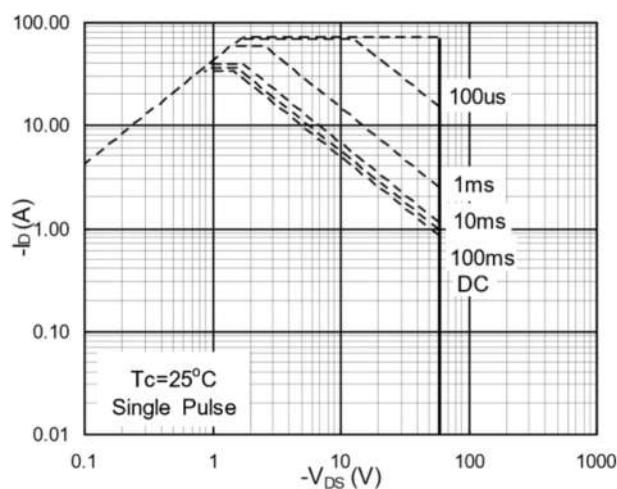


**Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$**

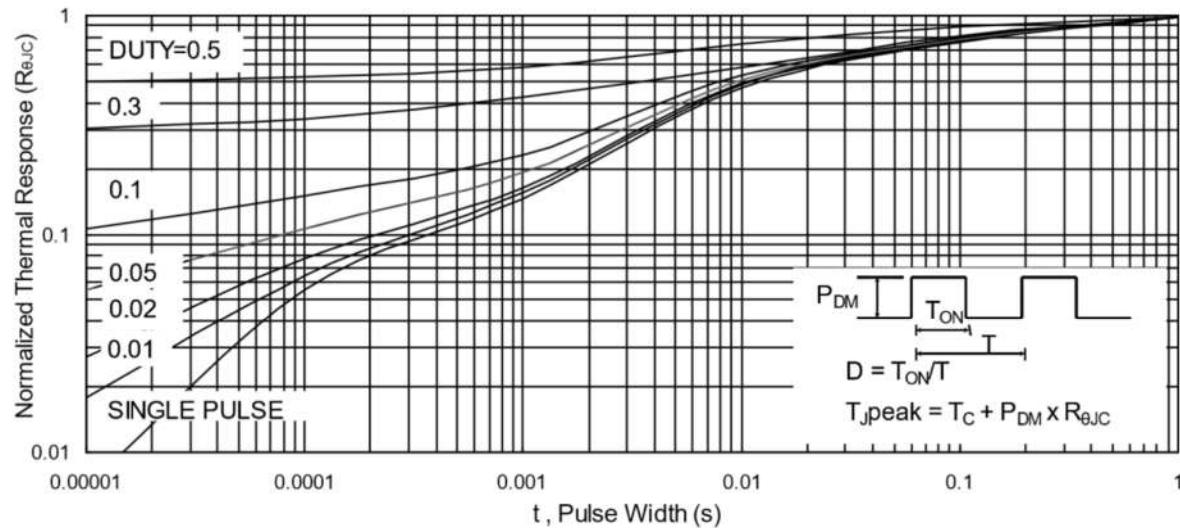
**Ratings and Characteristic Curves**



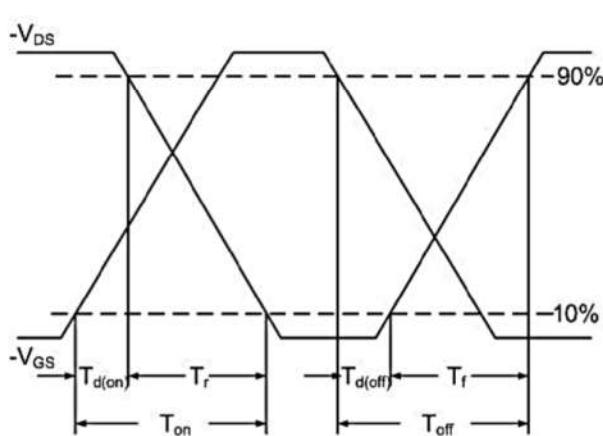
**Fig.7 Capacitance**



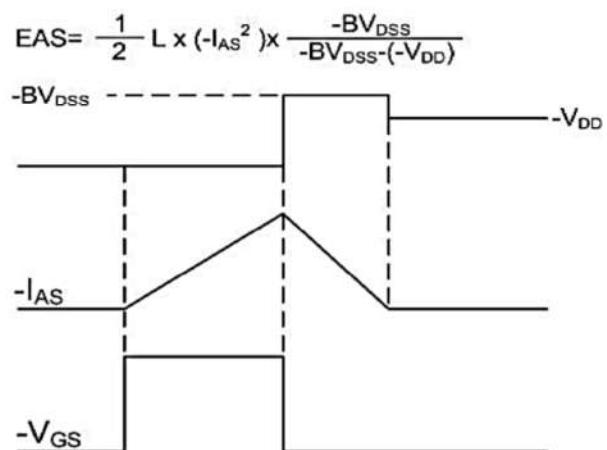
**Fig.8 Safe Operating Area**



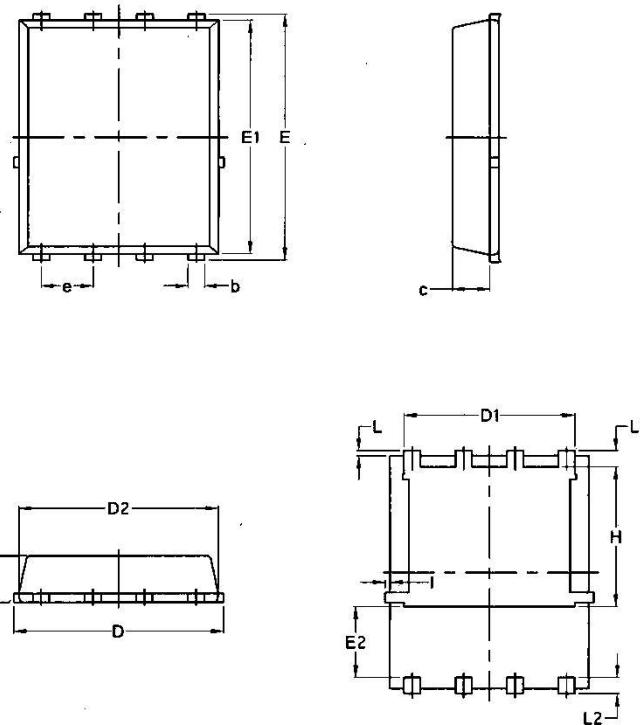
**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Waveform**

**Package Outline Dimensions Millimeters**
**PDFN5\*6-8L**


Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070